

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Examiner:

William D Coleman

Serial No.:

09/484,303

Group Art Unit:

2823

Filed:

January 18, 2000

Docket:

303.648US1

Title:

METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER,

SILVER, GOLD, AND OTHER METALS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS RCE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

Title: METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6900

Date 3-10-05

Marvin I. Reekn

Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 100 day of March, 2005.

FACIA LEE

Kacia Lee

PTO/SB/08A(10-01)
Approved for use through 10/31/2002, OMB 651-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 09/484,303 STATEMENT BY APPLICANT January 18, 2000 (Use as many sheets as necess **Filing Date** Ahn, Kie **First Named Inventor** 2823 **Group Art Unit** Coleman, William **Examiner Name** Attorney Docket No: 303.648US1 Sheet 1 of 1

US PATENT DOCUMENTS							
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate			
	US-2005/0023697-A1	02/03/2005	Ahn, K. Y., et al.	08/31/2004			
	US-2005/0023699-A1	02/03/2005	Ahn, K. Y., et al.	08/30/2004			
	US-5,000,818	03/19/1991	Thomas, M. E., et al.	05/18/1990			
	US-5,171,713	12/15/1992	Matthews, J. A.	01/28/1991			
	US-5,889,295	03/30/1999	Rennie, J., et al.	02/26/1997			
	US-5,969,398	10/19/1999	Murakami, T.	02/19/1998			
	US-6,361,667	03/26/2002	Kobayashi, M., et al.	03/16/1998			

FOREIGN PATENT DOCUMENTS								
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T²				

	OTHER	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
		MURARKA, S. P., et al., "Copper Metallization for ULSI and Beyond", <u>Critical</u> Reviews in Solid State and Materials Sciences, 20(2), (1995), 87-124	